



AOS
SEMICONDUCTOR

产品规格说明书

Product Data Sheet

AOS866xX(-G)

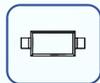
WEB | www.aossemi.cn 



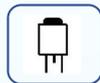
电源管理IC



通信接口芯片



二三极管



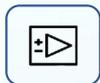
LDO稳压器



逻辑器件



MOSFETs



运算放大器



显示驱动



MCU单片机



光电器件



Zero-Drift, Rail-to-Rail I/O CMOS Operational Amplifiers

DESCRIPTIONS

The AOS866X is a low noise, low offset voltage and high voltage operational amplifier, which can be designed into a wide range of applications. The AOS866X has a gain bandwidth product of 11MHz, a slew rate of 15V/μs and a quiescent current of 2.0mA at wide power supply range.

The AOS866X is designed to provide optimal performance in low noise systems. It provides rail-to-rail output swing into heavy loads.

The AOS866X has over-temperature protection feature to guarantee the chip safe. The output of AOS866X will enter high impedance when die temperature reach around 170°C and will recover the function when the die temperature down to around 150°C.

The AOS866X is available in Green SOT23-5, SOP8, MSOP8 and SOP14 packages. It operates over an ambient temperature range of -40°C to +125°C under single power supplies of 4.5V to 36V or dual power supplies of ±2.25V to ±18V.

FEATURES

- Low Offset Voltage: ±5μV
- ★ Low Bias Current
- Gain Bandwidth Product: 11MHz
- Rail-to-Rail Output
- High Slew Rate: 15V/μs
- Low Quiescent Current: 2.0mA (TYP)
- Supply Voltage Range: 4.5V to 36V
- Over-Temperature Protection
- Low Noise: 8nV/√Hz at 1kHz
- Differential Input Voltage Up to Supply Rail, can Work as Comparator
- Extended Temperature: -40°C to +125°C
- Micro SIZE PACKAGES: SOT23-5, SOP8, MSOP8 and SOP14

APPLICATIONS

- Sensors
- Photodiode Amplification
- Active Filters
- Test Equipment
- Driving A/D Converters
- Industrial Control

Device Information(1)

PART NUMBER	PACKAGE	BODY SIZE(NOM)
AOS8661	SOT23-5	1.60mm × 2.92mm
	SOP8	4.90mm × 3.90mm
AOS8662	SOP8	4.90mm × 3.90mm
	MSOP8	3.00mm × 3.00mm
AOS8664	SOP14	8.65mm × 3.90mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.



PACKAGE/ORDERING INFORMATION⁽¹⁾

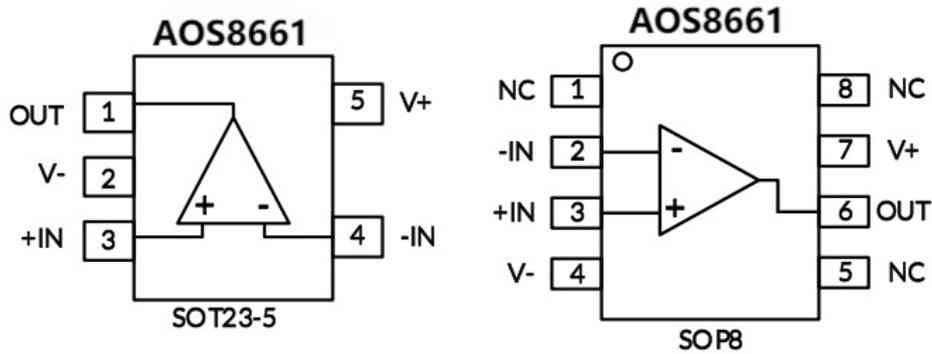
Orderable Device	Package Type	Pin	Channel	Op Temp(°C)	Device Marking ⁽²⁾	MSL ⁽³⁾	Package Qty
AOS8661XF-G	SOT23-5	5	1	-40°C~125°C	8661	MSL1	Tape and Reel , 3000
AOS8661XK-G	SOP8	8	1	-40°C ~125°C	AOS8661	MSL1	Tape and Reel , 4000
AOS8662XK-G	SOP8	8	2	-40°C~125°C	AOS8662	MSL1	Tape and Reel , 4000
AOS8662XM-G	MSOP8	8	2	-40°C~125°C	AOS8662	MSL1	Tape and Reel , 4000
AOS8664XP	SOP14	14	4	-40°C ~125°C	AOS8664	MSL3	Tape and Reel , 4000

NOTE:

- (1) This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the right-hand navigation.
- (2) There may be additional marking, which relates to the lot trace code information (data code and vendor code), the logo or the environmental category on the device.
- (3) MSL, The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications.



Pin Configuration and Functions (Top View)



Pin Description

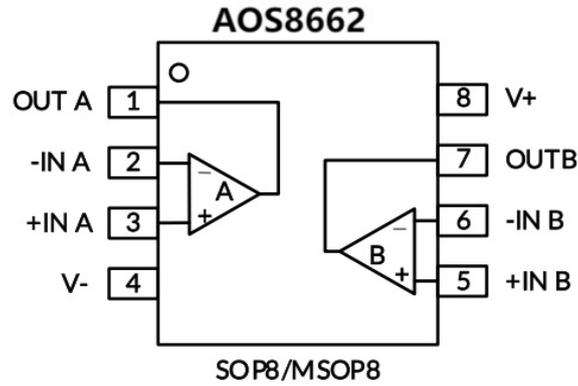
NAME	PIN		I/O ⁽¹⁾	DESCRIPTION
	SOT23-5	SOP8		
OUT	1	6	0	Output
V-	2	4	-	Negative (lowest) power supply
+IN	3	3	I	Positive (noninverting) input
-IN	4	2	I	Negative (inverting) input
V+	5	7	-	Positive (highest) power supply
NC ⁽²⁾	-	1, 5, 8	-	No internal connection (can be left floating)

(1) I = Input, 0 = Output.

(2) There is no internal connection. Typically, GND is the recommended connection to a heat spreading plane.



Pin Configuration and Functions (Top View)



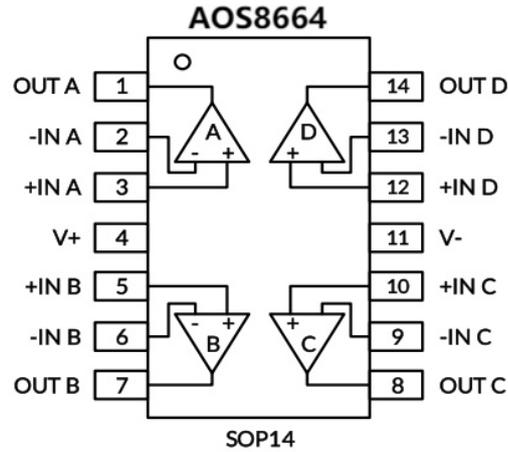
Pin Description

NAME	PIN	I/O ⁽¹⁾	DESCRIPTION
	SOP8/MSOP8		
-INA	2	I	Inverting input, channel A
+INA	3	I	Noninverting input, channel A
-INB	6	I	Inverting input, channel B
+INB	5	I	Noninverting input, channel B
OUTA	1	O	Output, channel A
OUTB	7	O	Output, channel B
V-	4	-	Negative (lowest) power supply
V+	8	-	Positive (highest) power supply

(1) I = Input, O = Output.



Pin Configuration and Functions (Top View)



Pin Description

NAME	PIN	I/O ⁽¹⁾	DESCRIPTION
	SOP14		
-INA	2	I	Inverting input, channel A
+INA	3	I	Noninverting input, channel A
-INB	6	I	Inverting input, channel B
+INB	5	I	Noninverting input, channel B
-INC	9	I	Inverting input, channel C
+INC	10	I	Noninverting input, channel C
-IND	13	I	Inverting input, channel D
+IND	12	I	Noninverting input, channel D
OUTA	1	O	Output, channel A
OUTB	7	O	Output, channel B
OUTC	8	O	Output, channel C
OUTD	14	O	Output, channel D
V-	11	-	Negative (lowest) power supply or ground (for single supply operation)
V+	4	-	Positive (highest) power supply

(1) I = Input, O = Output.



SPECIFICATIONS

Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

		MIN	MAX	UNIT	
Voltage	Supply, $V_s=(V+) - (V-)$		40	V	
	Signal input pin ⁽²⁾	(V-)-0.3	(V+)+0.3		
	Signal output pin ⁽³⁾	(V-)-0.3	(V+)+0.3		
	Differential input voltage	(V-) -(V+)	(V+) -(V-)		
Current	Signal input pin ⁽²⁾	-10	10	mA	
	Signal output pin ⁽³⁾	-10	10	mA	
	Output short-circuits ⁽⁴⁾	Continuous			
J _A	Package thermal impedance ⁽⁵⁾	SOT23-5		230	°C/W
		SOP8		110	
		MSOP8		170	
		SOP14		105	
Temperature	Operating range, T _A		-40	125	°C
	Junction, T _J ⁽⁶⁾		-40	150	
	Storage, T _{stg}		-65	150	
	Lead temperature (Soldering, 10sec)			260	

- (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.
- (2) Input terminals are diode-clamped to the power-supply rails. Input signals that can swing more than 0.3V beyond the supply rails should be current-limited to 10mA or less.
- (3) Output terminals are diode-clamped to the power-supply rails. Output signals that can swing more than 0.3V beyond the supply rails should be current-limited to $\pm 10\text{mA}$ or less.
- (4) Short-circuit to ground, one amplifier per package.
- (5) The package thermal impedance is calculated in accordance with JESD-51.
- (6) The maximum power dissipation is a function of $T_{J(\text{MAX})}$, R_{JA} , and T_A . The maximum allowable power dissipation at any ambient temperature is $P_D = (T_{J(\text{MAX})} - T_A) / R_{JA}$. All numbers apply for packages soldered directly onto a PCB.



ESD Ratings

The following ESD information is provided for handling of ESD-sensitive devices in an ESD protected area only.

			VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human-body model (HBM), JEDEC EIA /JESD22-A114	± 2000	V
		Charged-device model (CDM), ANSI/ESDA/JEDEC JS-002-2022	± 1500	



ESD SENSITIVITY CAUTION

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

Recommended Operating Conditions

Over operating free-air temperature range (unless otherwise noted).

		MIN	MAX	UNIT
Supply voltage, V _S = (V+) - (V-)	Single-supply	4.5	36	V
	Dual -supply	± 2.25	± 18	



ELECTRICAL CHARACTERISTICS

At $T_A = +25^\circ\text{C}$, $V_S = 36\text{V}$, $R_L = 10\text{k}$, Full ⁽⁹⁾ = -40°C to $+125^\circ\text{C}$, unless otherwise noted⁽¹⁾

PARAMETER	CONDITIONS	T_A	AOS866X			UNIT	
			MIN ⁽²⁾	TYP ⁽³⁾	MAX ⁽²⁾		
POWER SUPPLY							
V_S	Operating Voltage Range	Full	4.5		36	V	
I_Q	Quiescent Current per Amplifier	$V_S = 5\text{V}$	25 $^\circ\text{C}$		2.0	2.4	mA
			Full			2.6	
		$V_S = 36\text{V}$	25 $^\circ\text{C}$		2.1	2.5	
			Full			2.7	
PSRR	Power-Supply Rejection Ratio	$V_S = 4.5\text{V}$ to 36V	25 $^\circ\text{C}$	130	150	dB	
			Full	120			
INPUT							
V_{OS}	Input Offset Voltage	$V_S = 5\text{V}$, $V_{CM} = 2.5\text{V}$	25 $^\circ\text{C}$	-20	± 5	20	μV
			Full	-30		30	
		$V_S = 36\text{V}$, $V_{CM} = 18\text{V}$	25 $^\circ\text{C}$	-20	± 10	20	μV
			Full	-30		30	
$V_{OS} T_C$	Input Offset Voltage Drift	Full		± 0.1		$\mu\text{V}/^\circ\text{C}$	
I_B	Input Bias Current ⁽⁴⁾⁽⁵⁾	$V_S = 36\text{V}$, $V_{CM} = 18\text{V}$	25 $^\circ\text{C}$	-2.5	0.3	2.5	nA
			Full	-5		5	
I_{OS}	Input Offset Current ⁽⁴⁾	$V_S = 36\text{V}$, $V_{CM} = 18\text{V}$	25 $^\circ\text{C}$		0.3		nA
			Full	-5		5	
I_{IN}	Different Input Current	$V_S = 36\text{V}$, $V_{ID} = 36\text{V}$	25 $^\circ\text{C}$		1	10	μA
C_{IN}	Input Capacitance	Differential Mode	25 $^\circ\text{C}$		5		pF
		Common Mode	25 $^\circ\text{C}$		2.5		pF
A_{OL}	Open-Loop Voltage Gain	$R_{LOAD} = 10\text{k}$, $V_{OUT} = 0.5\text{V}$ to 35.5V	25 $^\circ\text{C}$	130	150		dB
			Full	120			dB
V_{CM}	Common-Mode Voltage Range	Full	(V-)		(V+)-1.5	V	
CMRR	Common-Mode Rejection Ratio	$V_{CM} = 0$ to 34.5V	25 $^\circ\text{C}$	130	150		dB
			Full	120			



OUTPUT							
	Output Swing from Positive Rail	$R_{LOAD} = 100k$ to $V_S/2$	25°C		10		mV
		$R_{LOAD} = 10k$ to $V_S/2$	25°C		95	150	
		$R_{LOAD} = 2k$ to $V_S/2$	25°C		470		
	Output Swing from Negative Rail	$R_{LOAD} = 100k$ to $V_S/2$	25°C		6		mV
		$R_{LOAD} = 10k$ to $V_S/2$	25°C		60	150	
		$R_{LOAD} = 2k$ to $V_S/2$	25°C		255		
ISC	Short-Circuit Current ⁽⁶⁾⁽⁷⁾	Source	25°C	45	60		mA
		Sink	25°C	90	100		
AC Specifications							
SR	Slew Rate ⁽⁸⁾	$G=1$, 10V Step	25°C		15		V/ μ s
GBW	Gain-Bandwidth Product		25°C		11		MHz
ts	Settling Time, 0.1%	$G=1$, 10V Step	25°C		5		μ s
t _{OR}	Overload Recovery Time		25°C		300		ns
PM	Phase Margin	$R_L=10k$, $C_L=50pF$	25°C		60		°
GM	Gain Margin	$R_L=10k$, $C_L=50pF$	25°C		10		dB
NOISE							
En	Input Voltage Noise	$V_S = 5V$, $f = 0.1Hz$ to 10Hz	25°C		0.2		μ Vpp
en	Input Voltage Noise Density ⁽⁴⁾	$f = 0.1kHz$	25°C		8		nV/ Hz
		$f = 1kHz$	25°C		8		
		$f = 10kHz$	25°C		8		
THD+N	Total Harmonic Distortion and Noise	$f = 1kHz$, $G = 1$, $R_L = 10k$, $V_{OUT} = 6V_{RMS}$			0.0004		%
Thermal Protection							
T _{SHDN}	Thermal Shutdown Temperature				170		°C
T _{SHDN}	Thermal Shutdown Hysteresis				20		



NOTE:

- (1) Electrical table values apply only for factory testing conditions at the temperature indicated. Factory testing conditions result in very limited self-heating of the device.
- (2) Limits are 100% production tested at 25°C. Limits over the operating temperature range are ensured through correlations using statistical quality control (SQC) method.
- (3) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration.
- (4) This parameter is ensured by design and/or characterization and is not tested in production.
- (5) Positive current corresponds to current flowing into the device.
- (6) The maximum power dissipation is a function of $T_{J(MAX)}$, R_{JA} , and T_A . The maximum allowable power dissipation at any ambient temperature is $P_D = (T_{J(MAX)} - T_A) / R_{JA}$. All numbers apply for packages soldered directly onto a PCB.
- (7) Short circuit test is a momentary test.
- (8) Number specified is the slower of positive and negative slew rates.
- (9) Specified by characterization only.



TYPICAL CHARACTERISTICS

NOTE: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. At $T_A = +25^\circ\text{C}$, $V_S = \pm 18\text{V}$, $R_L = 10\text{k}\Omega$, unless otherwise specified.

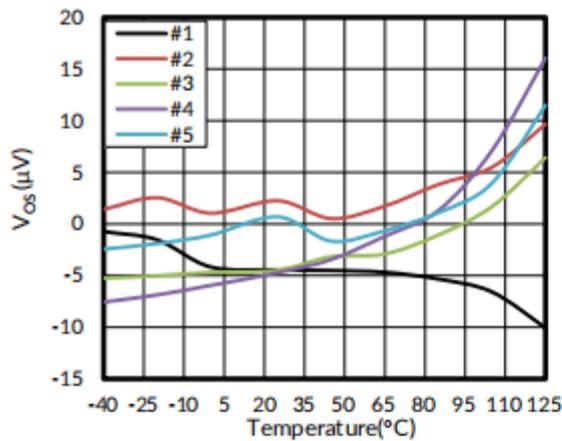


Figure 1. V_{OS} at 36V V_S , 18V V_{CM} vs Temperature

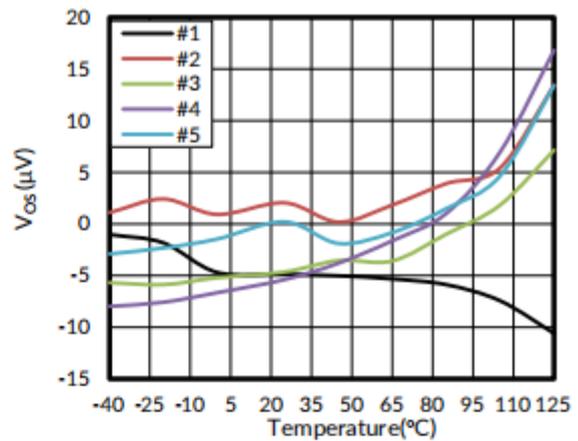


Figure 2. V_{OS} at 5V V_S , 2.5V V_{CM} vs Temperature

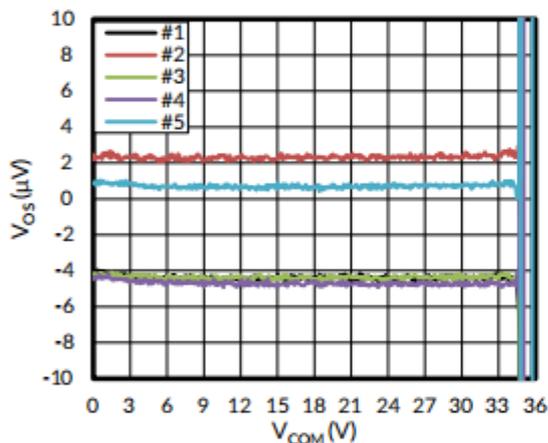


Figure 3. Offset Voltage vs Common Mode Voltage

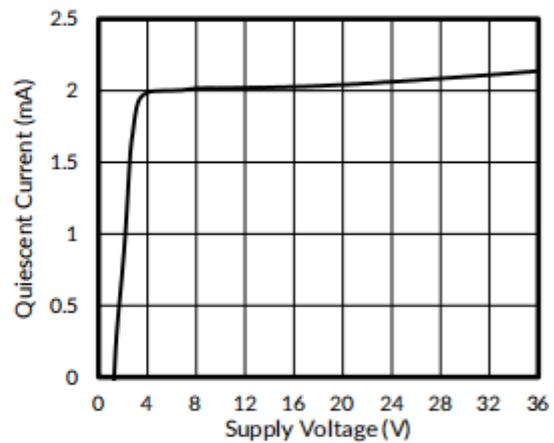


Figure 4. Quiescent Current vs Supply Voltage

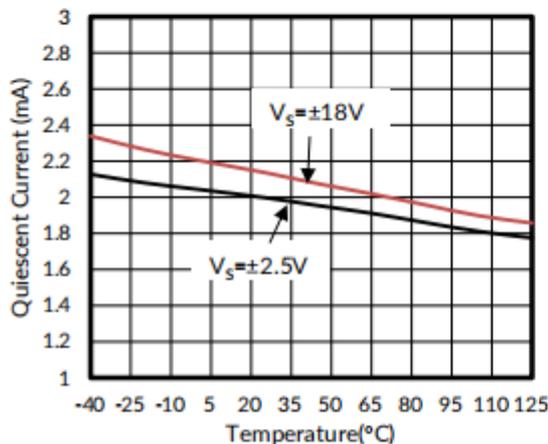


Figure 5. Quiescent Current vs Temperature

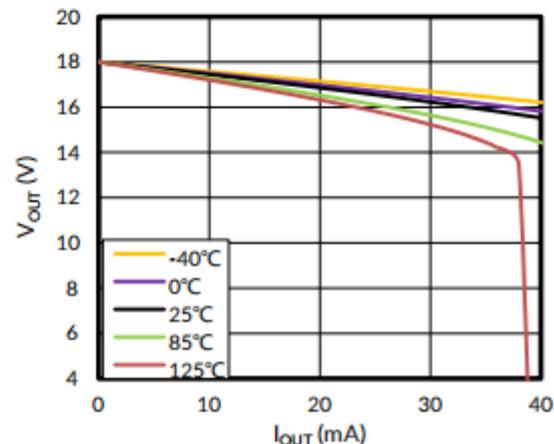


Figure 6. V_{OUT} vs I_{OUT} , Source

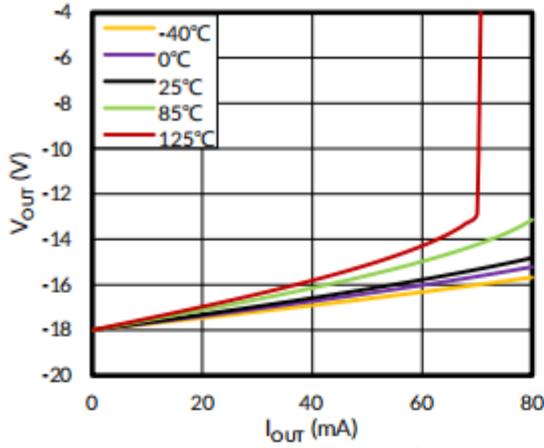


Figure 7. V_{OUT} vs I_{OUT} , Sink

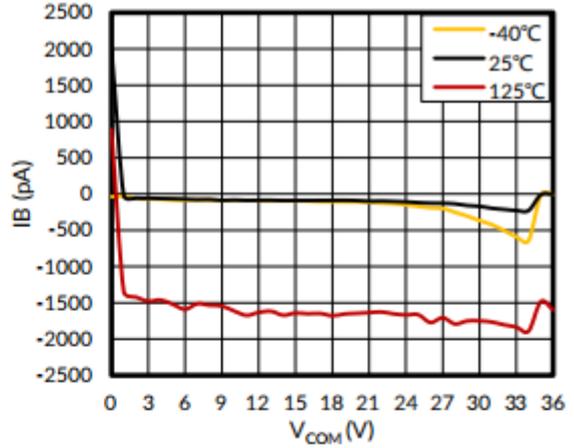


Figure 8. I_B vs V_{COM}

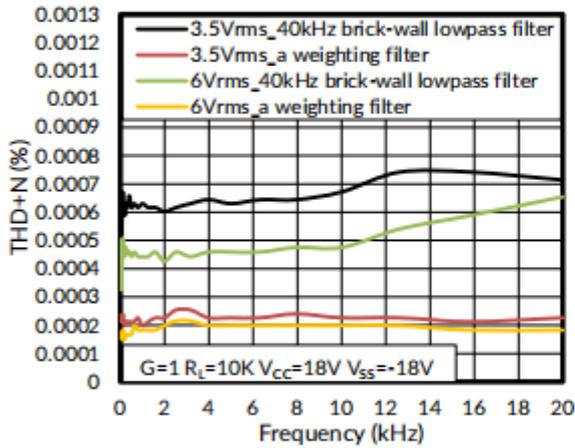


Figure 9. THD+N VS Frequency

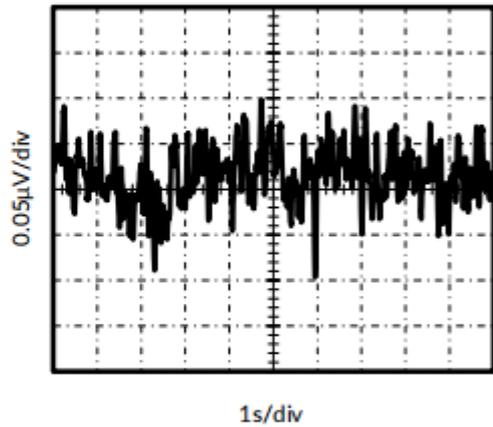


Figure 10. 0.1Hz to 10Hz Input Voltage Noise

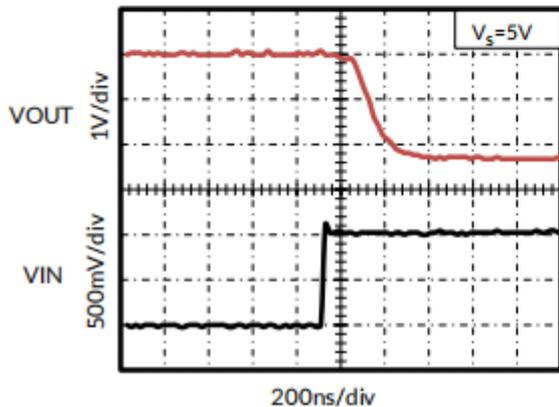


Figure 11. Positive Overload Recovery

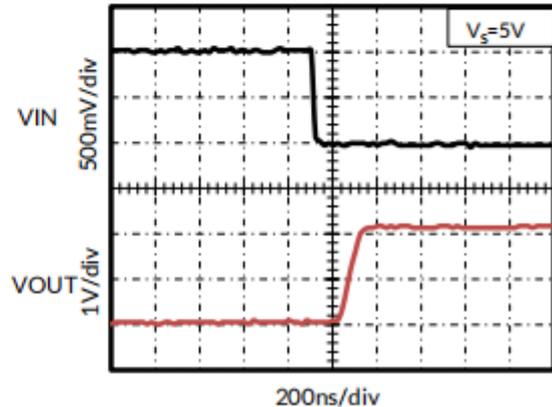


Figure 12. Negative Overload Recovery

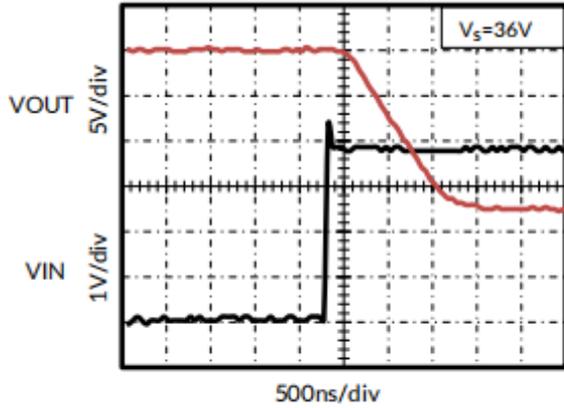


Figure 13. Positive Overload Recovery

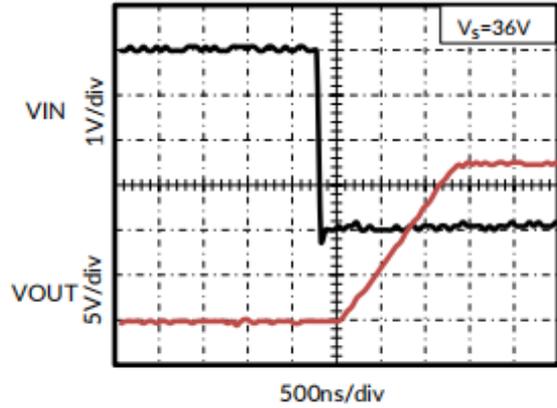


Figure 14. Negative Overload Recovery

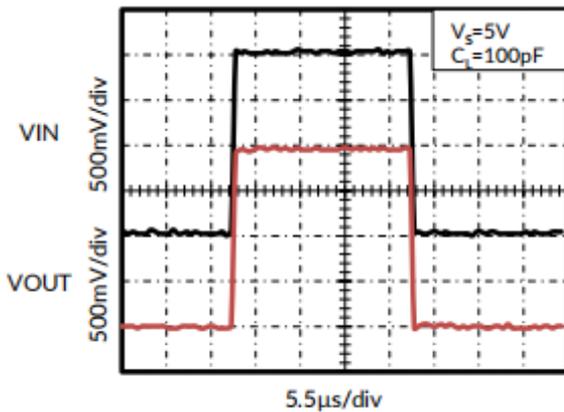


Figure 15. Large Signal Step Response

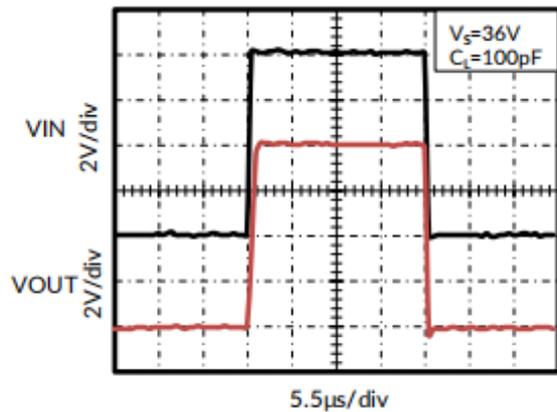


Figure 16. Large Signal Step Response

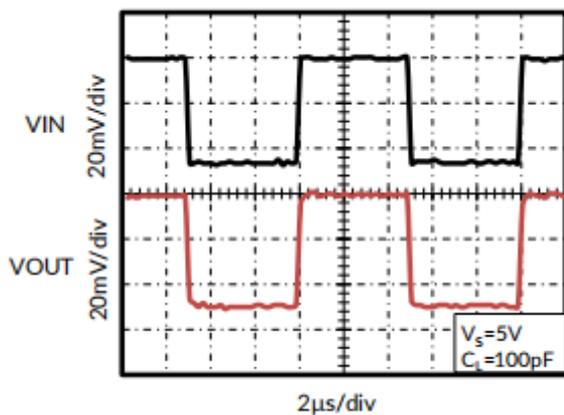


Figure 17. Small Signal Step Response

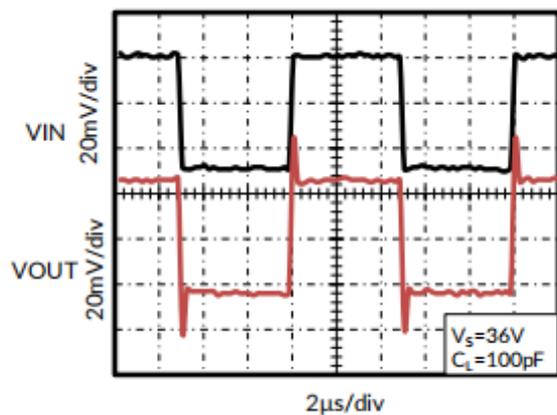
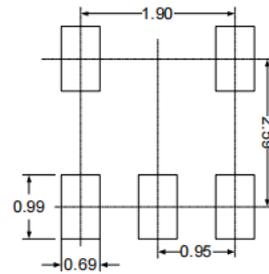
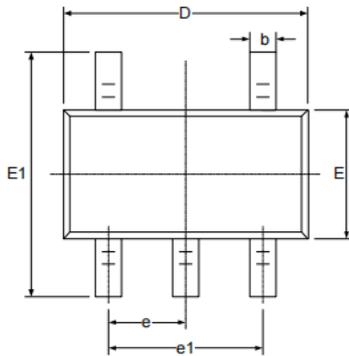


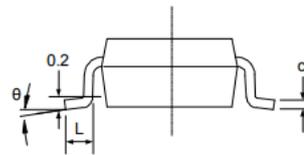
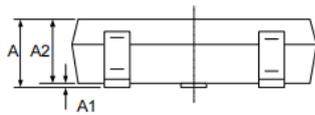
Figure 18. Small Signal Step Response



PACKAGE OUTLINE DIMENSIONS
SOP23-5⁽³⁾



RECOMMENDED LAND PATTERN (Unit: mm)



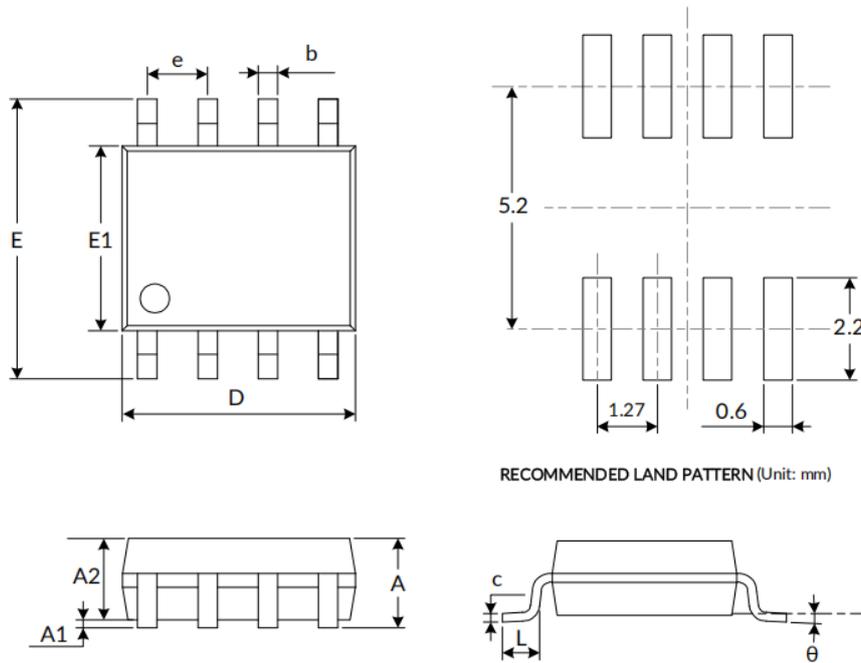
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A ⁽¹⁾	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D ⁽¹⁾	2.820	3.020	0.111	0.119
E ⁽¹⁾	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC) ⁽²⁾		0.037(BSC) ⁽²⁾	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
	0°	8°	0°	8°

NOTE:

1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.



SOP-8⁽³⁾



RECOMMENDED LAND PATTERN (Unit: mm)

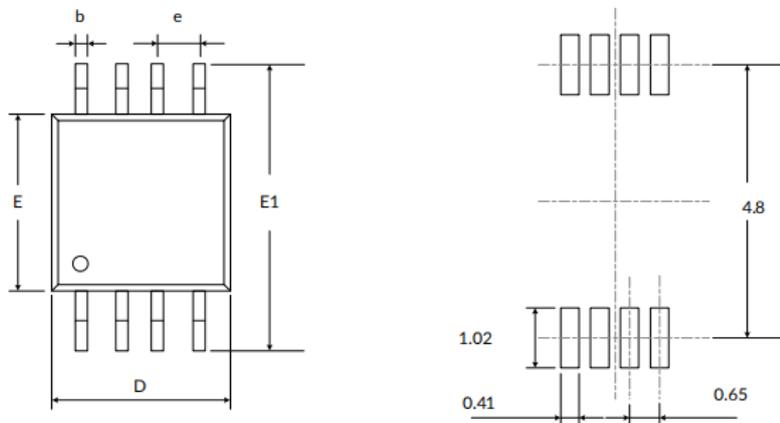
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A ⁽¹⁾	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D ⁽¹⁾	4.800	5.000	0.189	0.197
e	1.270(BSC) ⁽²⁾		0.050(BSC) ⁽²⁾	
E	5.800	6.200	0.228	0.244
E1 ⁽¹⁾	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
	0°	8°	0°	8°

NOTE:

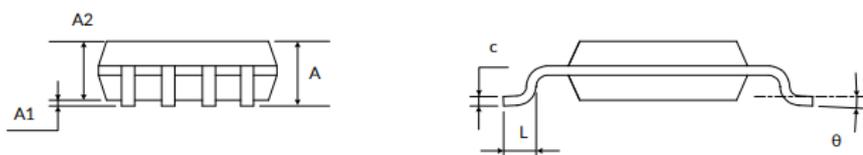
1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.



MSOP8⁽³⁾



RECOMMENDED LAND PATTERN (Unit: mm)



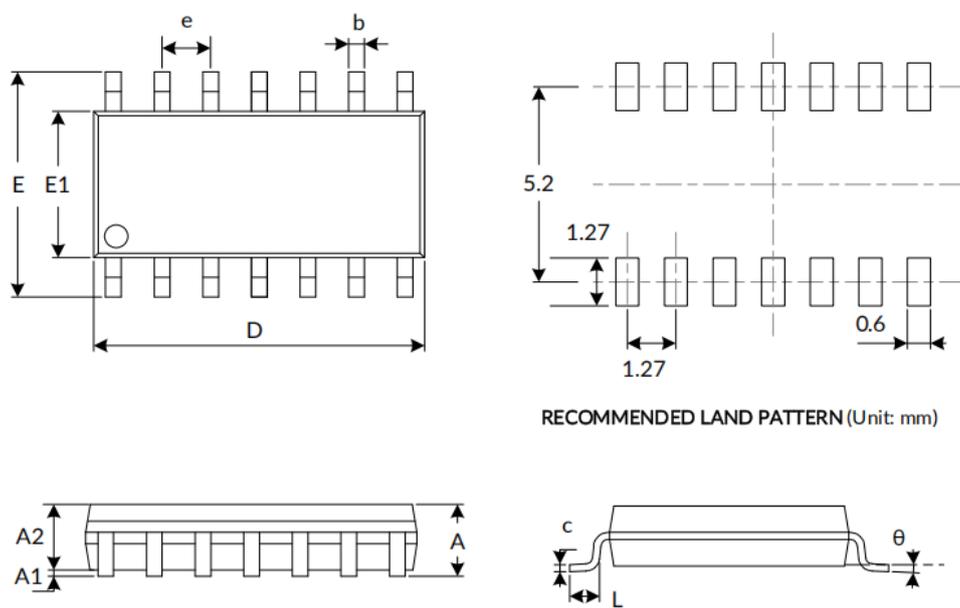
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A ⁽¹⁾	0.820	1.100	0.032	0.043
A1	0.020	0.150	0.001	0.006
A2	0.750	0.950	0.030	0.037
b	0.250	0.380	0.010	0.015
c	0.090	0.230	0.004	0.009
D ⁽¹⁾	2.900	3.100	0.114	0.122
e	0.650 (BSC) ⁽²⁾		0.026 (BSC) ⁽²⁾	
E ⁽¹⁾	2.900	3.100	0.114	0.122
E1	4.750	5.050	0.187	0.199
L	0.400	0.800	0.016	0.031
	0°	6°	0°	6°

NOTE:

1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.



SOP-14⁽³⁾



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A ⁽¹⁾	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.310	0.510	0.012	0.020
c	0.100	0.250	0.004	0.010
D ⁽¹⁾	8.450	8.850	0.333	0.348
e	1.270(BSC) ⁽²⁾		0.050(BSC) ⁽²⁾	
E	5.800	6.200	0.228	0.244
E1 ⁽¹⁾	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
	0°	8°	0°	8°

NOTE:

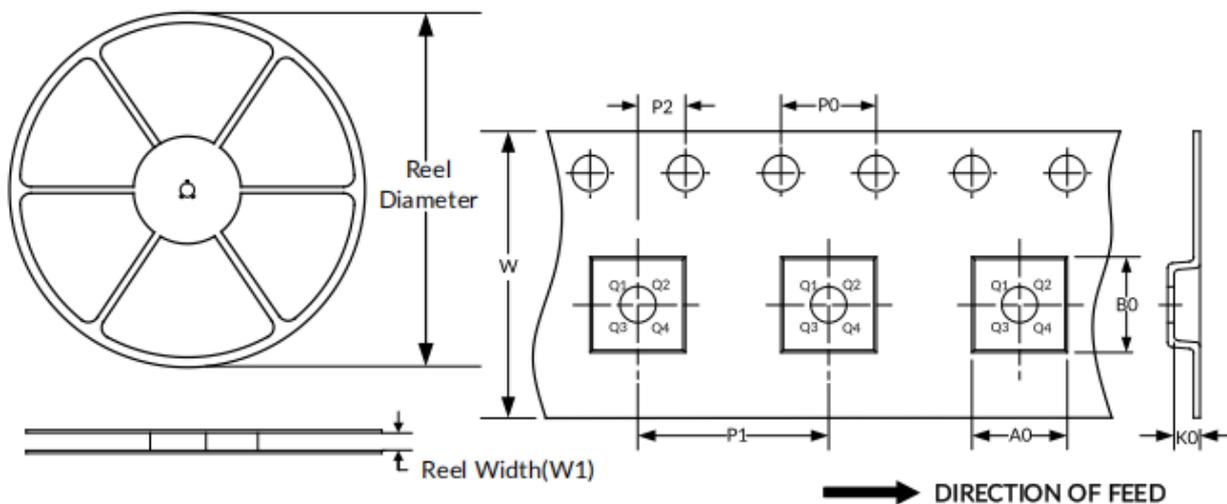
1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.



TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSION



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pi n1 Quadrant
SOT23-5	7''	9.5	3.20	3.20	1.40	4.0	4.0	2.0	8.0	Q3
SOP8	13''	12.4	6.40	5.40	2.10	4.0	8.0	2.0	12.0	Q1
MSOP8	13''	12.4	5.20	3.30	1.50	4.0	8.0	2.0	12.0	Q1
SOP14	13''	16.4	6.60	9.30	2.10	4.0	8.0	2.0	16.0	Q1

NOTE:

1. All dimensions are nominal.
2. Plastic or metal protrusions of 0.15mm maximum per side are not included.